

# INTERNATIONAL STANDARD

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**Mechanical standardization of  
semiconductor devices –**

**Part 6-13:  
Design guideline of open-top-type sockets for  
Fine-pitch Ball Grid Array and Fine-pitch Land  
Grid Array (FBGA/FLGA)**



Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

## CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references .....	5
3 Terms and definitions .....	5
4 Socket code .....	5
4.1 Construction of socket code .....	5
4.2 Symbols .....	6
5 Terminal number .....	6
6 Socket nominal dimension.....	6
7 Socket length and width .....	7
8 Reference symbols and schematics.....	7
8.1 Outline drawings .....	7
8.2 Reference symbols and schematics of recommended socket mounting pattern on printed circuit board.....	9
8.3 Overall dimensions.....	10
8.4 Recommended dimensions of socket mounting pattern on printed circuit board .....	14
9 Individual outline drawing standard registration .....	15
Table 1 – Overall dimensions.....	10
Table 2 – Socket dimensions .....	12
Table 2a – Socket dimensions for Group 1, 2 and 3 (square socket) .....	12
Table 2b – Socket dimension for Group 4 (square or rectangular socket).....	13
Table 3 – Socket mounting dimensions .....	14
Table 4 – Registration table .....	15
Figure 1 – Outline drawings of the socket .....	8
Figure 2 – Applicable package outline.....	8
Figure 3 – Socket mounting pattern .....	9

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

### Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)

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International Standard IEC 60191-6-13 has been prepared by subcommittee 47D: Mechanical standardization for semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/681/FDIS	47D/692/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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A list of all the parts in the IEC 60191 series, under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

## **MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –**

### **Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)**

#### **1 Scope**

This part of IEC 60191 gives a design guideline of open-top-type semiconductor sockets for Fine-pitch Ball Grid Array ("FBGA" hereafter) and Fine-pitch Land Grid Array ("FLGA" hereafter). This standard is intended to establish the outline drawings and dimensions of the open-top-type socket out of the test and burn-in sockets applied to FBGA and FLGA.

#### **2 Normative references**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-2, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 60191-6:2004, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*